

Final Product/Process Change Notification Document #:FPCN23100Z

Issue Date:05 Nov 2020

| Title of Change: | FAD7191M1X(SO14) Assembly and FT transfer from HANA to Carmona | |
|--|---|--|
| Proposed Changed Material First Ship Date: | 05 Nov 2021 or earlier if approved by customer | |
| Current Material Last Order Date: | NA Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability. | |
| Current Material Last Delivery Date: | NA The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory | |
| Product Category: | Active components – Integrated circuits | |
| Contact information: | Contact your local ON Semiconductor Sales Office or Hyunkyung.Park@onsemi.com | |
| PCN Samples Contact: | Contact your local ON Semiconductor Sales Office to place sample order or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com> | |
| Sample Availability Date: | 26 Oct 2020 | |
| PPAP Availability Date: | 26 Oct 2020 | |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office or Rhica.Loredo@onsemi.com | |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com. | |
| Change Category | | |
| Category | Type of Change | |
| All | Any change with impact on agreed upon contractual agreements | |
| Process - Assembly | Change of mold compound, Die attach material | |

Description and Purpose:

| | Before Change Description | After Change Description |
|--------------------|------------------------------|---------------------------------------|
| LeadFrame Supplier | HDS | ASM |
| Die Attach | QMI519 5CC 19G CON | ABLESTIK ABP 8062T |
| Mold Compound | Sumitomo G700LTD | EME G700LS |
| Assembly Site | HANA Semiconductor, Thailand | ON Semiconductor Carmona, Philippines |
| FT Site | HANA Semiconductor, Thailand | ON Semiconductor Carmona, Philippines |

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| | From | То |
|------------------------|--|---------------------------------|
| Product marking change | Tracecode:H(WLYWW) Line2:FAD7191M1X | Line1: FAD7191 Line2: A(YWW) |

| Reason / Motivation for Change: | Quality improvement |
|--|---|
| Anticipated impact on fit, form, function, reliability, product safety or manufacturability: | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts. |

Sites Affected:

Change:

| ON Semiconductor Sites | | External Foundry/Subcon Sites |
|--------------------------------------|---|-------------------------------|
| ON Semiconductor Carmona, Philippine | S | HANA Semiconductor, Thailand |
| Marking of Parts/ Traceability of | The affected products will have a standard marking from OSPI as below. Line1: FAD7191 | |

Line2: A(YWW)

Reliability Data Summary:

QV DEVICE NAME FAD7191M1X RMS 070434 PACKAGE SO14

| Test | Specification | Condition | Interval | Results |
|-------|---------------------|-----------------------------------|----------|---------|
| HTSL | JESD22-A103 | Ta= 150°C | 1008 hrs | 0/231 |
| TC | JESD22-A104 | Ta= -65°C to +150°C | 1000сус | 0/231 |
| uHAST | JESD22-A118 | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs | 0/231 |
| PC | J-STD-020 JESD-A113 | MSL 1 @ 260 °C | | |
| RSH | JESD22- B106 | Ta = 260C, 10 sec | | 0/30 |
| SD | JSTD002 | Ta = 245C, 5 sec | | 0/45 |

NOTE: AEC-1 pager is attached.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file/

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

| Current Part Number | New Part Number | Qualification Vehicle |
|---------------------|-----------------|-----------------------|
| FAD7191M1X | NA | FAD7191M1X |

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